

# DDR2 Code Information

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## Component

### Part Number Decoder

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# Part Number Decoder

**K** **4** **T** **X** **X** **X** **X** **X** **X** **X** - **X** **X** **X** **X** **X** **X** **X**  
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

## 1. Memory (K)

## 2. DRAM : 4

## 3. Small Classification

T : DDR2 SDRAM

## 4~5. Density

56 : 256Mb

51 : 512Mb

1G : 1G

2G : 2G

4G : 4G

## 6~7. Bit Organization

04 : x4

06 : x4 Stack

07 : x8 Stack

08 : x8

16 : x16

26 : x4 Stack (JEDEC Standard)

27 : x8 Stack (JEDEC Standard)

## 8. # of Internal Banks

3 : 4 Banks

4 : 8 Banks

## 9. Interface, VDD, VDDQ

Q : SSTL\_18, 1.8V, 1.8V

## 10. Generation

M : M-die

A : A-die

B : B-die

C : C-die

D : D-die

E : E-die

F : F-die

G : G-die

H : H-die

I : I-die

Q : Q-die

R : R-die

## 11. "-"

## 12. Package

Z : FBGA (Lead-Free)

J : FBGA DDP (Lead-Free)

H : FBGA (Lead-Free & Halogen-Free)

M : FBGA DDP (Lead-Free & Halogen-Free)

T : FBGA DSP (Lead-Free & Halogen-Free, Thin)

B : FBGA (Lead-Free & Halogen-Free, Flip Chip)

## 13. Temp, Power

C : Commercial Temp.(0°C ~ 85°C), Normal Power

L : Commercial Temp.(0°C ~ 85°C), Low Power

Y : Commercial Temp.(0°C ~ 85°C), Low VDD(1.35V)

## 14~15. Speed (Wafer/Chip Biz/BGD: 00)

CC : DDR2-400 (200MHz@CL=3, tRCD=3, tRP=3)

D5 : DDR2-533 (266MHz@CL=4, tRCD=4, tRP=4)

E6 : DDR2-667 (333MHz@CL=5, tRCD=5, tRP=5)

F7 : DDR2-800 (400MHz@CL=6, tRCD=6, tRP=6)

E7 : DDR2-800 (400MHz@CL=5, tRCD=5, tRP=5)

**K 4 T X X X X X X X - X X X X X X X**  
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

## 16. Packing "Packing Type Reference"

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

| Divide    | Packing Type              | New Marking |
|-----------|---------------------------|-------------|
| Component | TAPE & REEL               | T           |
|           | Other ( Tray, Tube, Jar ) | 0 ( Number) |
|           | Stack                     | S           |
| Module    | MODULE TAPE & REEL        | P           |
|           | MODULE Other Packing      | M           |

## 17~18. Customer "Customer List Reference"